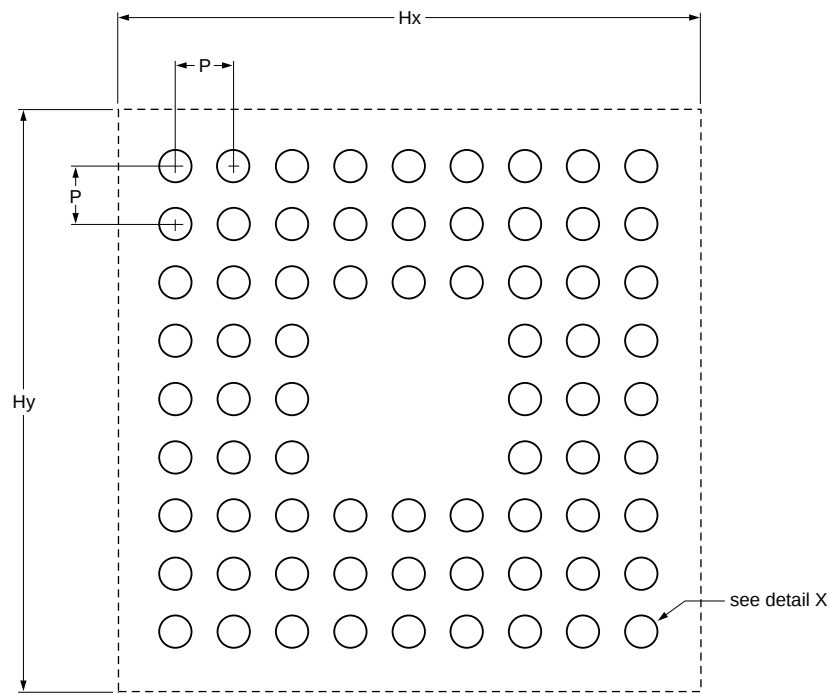


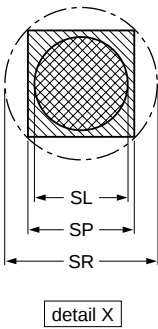
Footprint information for reflow soldering of TFBGA56 package

SOT911-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	4.400	4.900